	2 (providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing) 2 ("5249100"   "6300678").PN. 6 5249100.URPN. 7 ("3645785"   "3855693"   "4702941"   "4918811").PN. 8 ("4949455"   "5041901"   "5061552"   "5145104"   "5334804"   "5410807"	USPAT; US-PGPUB, EPO; JPO; DERWENT USPAT USPAT USPAT USPAT	Time stamp  2002/07/12 16:18  2002/07/12 15:58 2002/07/12 15:59 2002/07/12
	((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing) ("5249100"   "6300678").PN.  5249100.URPN.  ("3645785"   "3855693"   "4702941"   "4918811").PN.  ("4949455"   "5041901"   "5061559"	US-PGPUB, EPO; JPO; DERWENT USPAT USPAT USPAT	2002/07/12 15:58 2002/07/12 15:59
: :	sealing) ("5249100"   "6300678").PN.  5249100.URPN.  ("3645785"   "3855693"   "4702941"   "4918811").PN.  6300678.URPN.	US-PGPUB, EPO; JPO; DERWENT USPAT USPAT USPAT	2002/07/12 15:58 2002/07/12 15:59
: :	2 ("5249100"   "6300678").PN. 6 5249100.URPN. 4 ("3645785"   "3855693"   "4702941"   7 4918811").PN. 6 6300678.URPN. 7 ("4949455"   "5041901"   "5061550"	EPO; JPO; DERWENT USPAT USPAT USPAT	2002/07/12 15:58 2002/07/12 15:59
: :	2 ("5249100"   "6300678").PN. 6 5249100.URPN. 4 ("3645785"   "3855693"   "4702941"   "4918811").PN. 6300678.URPN. 6 ("4949455"   "5041901"   "5061550"	DERWENT USPAT USPAT USPAT	2002/07/12 15:58 2002/07/12 15:59
: <u>S</u>	5249100.URPN.  ("3645785"   "3855693"   "4702941"   "4918811").PN. 6300678.URPN.  ("4949455"   "5041901"   "5061550"	USPAT	15:58 2002/07/12 15:59
: <u>S</u>	("3645785"   "3855693"   "4702941"   "4918811").PN. 6300678.URPN.	USPAT	15:58 2002/07/12 15:59
: <u>S</u>	("3645785"   "3855693"   "4702941"   "4918811").PN. 6300678.URPN.	USPAT	15:59
: <u>c</u>	1 6300678.URPN.		15:59
9	1 6300678.URPN.		2002/07/12
9	1   6300678.URPN.	USPAT	
	9 ("4949455"   "5041901"   "5061550"	USPAT	15:59
	9 ("4949455"   "5041901"   "5061552"		2002/07/12
g	751451047   75001001   3001352"	1	16:00
9	) VIIVIUT   "5334807"   #64166699 ;	USPAT	2002/07/12
9	1 3333003"   "5642261"   #E010E10#\	Ì	16:00
	("4949455"   "5041901"   "5061552"		
	"5145104"   "5334804"   "5410807"	USPAT	2002/07/12
	"5533665"   "5642261"   "5912510").PN.		16:02
0	6413849.URPN.		_
		USPAT	2002/07/12
8	("4634041"   "4970570"   "5440000"		16:02
	1 2340010"   "5640052"   #674006"	USPAT	2002/07/12
	"6054652"   "6077725"\ DN	1	16:03
17	5640052.URPN.	1	-
		USPAT	2002/07/12
2	6054652.URPN		16:04
		USPAT	2002/07/12
8	("4634041"   "4970570"   "5440000"		16:08
	"5448016"   "5640052"   "57102.55"	USPAT	2002/07/12
	"6054652"   "6077725"\ PN		16:09
0	6413849.URPN		
		USPAT	2002/07/12
8	("4634041"   "4970570"   "5440000"		16:09
	"5448016"   "5640052"   "5710057"	USPAT	2002/07/12
	"6054652"   "60777725"\		16:09
4	("5421083"   "5422675"   "555555		
	"5834705"\ PM	USPAT	2002/07/12
5986	((pin adi grid adi amma)		16:09
	(method process)	USPAT;	2002/07/12
		US-PGPUB;	16:14
		EPO; JPO;	
170	(((pin adi grid adi ampan)	DERWENT	
	(method process) and it	USPAT;	2002/07/12
l	F-00005// and Jig	US-PGPUB;	16:14
ĺ		EPO; JPO;	
55	((((pin adi grid adi anno)	DERWENT	
	(method process)) and sime and	USPAT;	2002/07/12
	process, and jig, and polymer	US-PGPUB;	16:14
1			
51	(((((pin adj grid adj array)		
	(method process)) and dial		2002/07/12
	not ((providing near3 substrate)	US-PGPUB;	16:15
	((attaching soldering) noon2	EPO; JPO;	
	(encapsulant encapsulating ongar-with	DERWENT	
	searrid))		
12	(((((pin adi grid adi array) mes)		
1	(method process)) and iid and not (		2002/07/12
1 4	100 ((Providing near) substrate() and	US-PGPUB;	16:16
j.	((actaching Soldering) near? nin(	EPO; JPO;	1
- 1	(encapsulant encapsulating ongonius )	DERWENT	
	sealing))) and substrate and related		1
l r	pad solder and		
	providing near3 substants)		
1 6	(arraching goldoning) o		2002/07/12
1		US-PGPUB;   1	16:18
		EPO; JPO;	ľ
	17 2 8 0 8 4 5986 170 55	("4634041"   "4970570"   "5442239"   "5448016"   "5640052"   "5718367"   "6054652"   "6077725").PN. ("5421083"   "5432675"   "5543586"   "5834705").PN. ((pin adj grid adj array) pga) and (method process)  (((pin adj grid adj array) pga) and (method process)) and jig) and polymer  ((((pin adj grid adj array) pga) and (method process)) and jig) and polymer  (((((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and (((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing)) ((((((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))) and substrate and solder and pad ((providing near3 substrate) and ((attaching soldering) near3 pin)	"5640052"   "6077725").PN.   USPAT

(applying near3 (polymer polymeric polymide plastic))  (applying near3 (polymer polymeric polymeric polymide plastic))  DERWENT 2002/07/12 US-PGPUB; EPO; JPO; DERWENT	83	18	(providing near3 substrate) and ((attaching soldering) near3 pin) and (applying near3 polymer)  ((attaching soldering) near3 pin) and (applying near3 (polymer polymeric polyimide plastic))	US-PGPUB; EPO; JPO;	
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